

Teradyne Extends Memory Test Capabilities with New Magnum VU Test System

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UPBx Module Supports Protocol for UFS 3.0 and PCIe Gen 4

NORTH READING, Mass., May 22, 2019 (GLOBE NEWSWIRE) -- Teradyne, Inc. (NASDAQ:TER), a leading supplier of automated test solutions, has announced the new Universal Protocol Board (UPBx), a module for its Magnum VU memory test system that enables testing of high-speed memory devices, popular in cutting edge mobile phones and tablets.

As mobile devices offer higher resolution video, virtual reality (VR) and augmented reality (AR) applications, they are adopting higher speed NAND storage based on the Universal Flash Storage (UFS) 3.0. UFS 3.0 devices feature interface speeds up to 16Gbps per lane for real-time application performance like faster boot, faster multimedia and higher gaming performance.

Teradyne has miniaturized the UPBx to eliminate the traditional cabling between the test instrument and device under test (DUT). Instead, the UPBx is directly docked to the socket board. This Near DUT Test (NDT) architecture dramatically shortens the signal path, increasing performance, reducing latency and providing better emulation of the real system environment.

Magnum VU is a flexible, superset test platform that proves the performance and functionality of all NAND products, both cutting edge UFS 3.0 and PCIe Gen 4 mobile and automotive devices, as well as legacy NAND products such as UFS 2.1, PCIe Gen 3, e.MMC, ONFI and Toggle. Raw NAND for the solid-state drive (SSD) storage is also supported for enterprise and data center servers and personal computers. Based on competitive benchmarks, Teradyne believes the new UPBx makes Magnum VU the industry's highest performance, highest throughput NAND Protocol test platform.

"The innovative features in the UPBx demonstrate the flexibility and performance of the Magnum VU, as well as our commitment to staying ahead of the market so our customers can embrace the latest memory technology and know that their Magnum tester will support that technology," said Tim Moriarty, President of Teradyne's Memory Business Unit. "It's this execution and close attention to the market that has made the Magnum VU the de facto industry standard platform with over 80% market share."

The UPBx is the direct replacement for Teradyne's first generation UPB instrument for easy upgrades. The UPBx is available now. For more information, visit: <https://www.teradyne.com/products/test-solutions/semiconductor-test/magnum>.

About Teradyne

[Teradyne](https://www.teradyne.com) (NASDAQ:TER) brings high-quality innovations such as smart devices, life-saving medical equipment and data storage systems to market, faster. Its advanced test solutions for semiconductors, electronic systems, wireless devices and more ensure that products perform as they were designed. Its Industrial Automation offerings include collaborative and mobile robots that help manufacturers of all sizes improve productivity and lower costs. In 2018, Teradyne had revenue of \$2.1 billion and today employs 5,000 people worldwide. For more information, visit [teradyne.com](https://www.teradyne.com). Teradyne® is a registered trademark of Teradyne, Inc. in the U.S. and other countries.

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The logo for Teradyne, consisting of the word "TERADYNE" in a bold, blue, sans-serif font.

Source: Teradyne, Inc.